ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® Material Comp © Copyright 2005. I international and Pa	PC. Bannockl	burn, Illinois, A	ll rights reserved utions.	under both	This docum level parts, t	ent is a declarati the declaration e	on of the su	ibstances v s all lower	within the manufactule level materials for w	urer listed which the	item. Note manufactur	: if the item is an as rer has engineering	sembly with lower responsibility.	
				Form Type Distribute					rials and N	als and Mfg Information				
Supplier Information														
Company name* Compa			ompany unique ID			Unique ID Authority				Respor	Response Date*			
onsemi										2023-0	2023-06-08			
Contact Name Title - Contact			act			Phone - Contact*				Email	Email - Contact*			
Product-Env-Stewards Product En			Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Repr			presentative			Phone - Representative*				Email	Email - Representative*			
Product-Env-Stewards Product H			duct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Effective Date Version Manufacturin		Ianufacturing Site		Weight*	UOM	Unit Type	
	NCV856	NCV8560MN150R2G 1.5V LDO		OO WITH ENABLE		2023-06-08		M	MY1		20.0	mg	Each	
Manufacturing Proccess Informa	tion													
Terminal Plating / Grid Array M	aterial	Ferminal Base A	Alloy J-STD-020 MSL Ra		L Rating	Peak Proce	Process Body Temperat		ure Max Time at Peak Temper		ture Nur	nber of Reflow Cyd	les	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy	1			<b>260</b> C		С	30 seco		seconds 3			
Comments														
evel 1 - maximum time at peak temperat	ure during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead b), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl nthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.2	mg	Supplier	Silicon (Si)	7440-21-3		0.2	mg
Die Attach	0.45	mg	Supplier	Silver (Ag)	7440-22-4		0.3375	mg
			Supplier	Epoxy resins	129915-35-1		0.1125	mg
Lead Frame 6	6.97	mg	Supplier	Silver (Ag)	7440-22-4		1.9446	mg
			Supplier	Iron (Fe)	7439-89-6		0.0767	mg
			Supplier	Copper (Cu)	7440-50-8		4.9487	mg
Mold Compound-Black	10.0	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.8	mg
			Supplier	Carbon Black (C)	1333-86-4		0.05	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.2	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		8.65	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.3	mg
Plating	0.71	mg	Supplier	Tin (Sn)	7440-31-5		0.71	mg
Wire Bond - Au	1.67	mg	Supplier	Gold (Au)	7440-57-5		1.67	mg